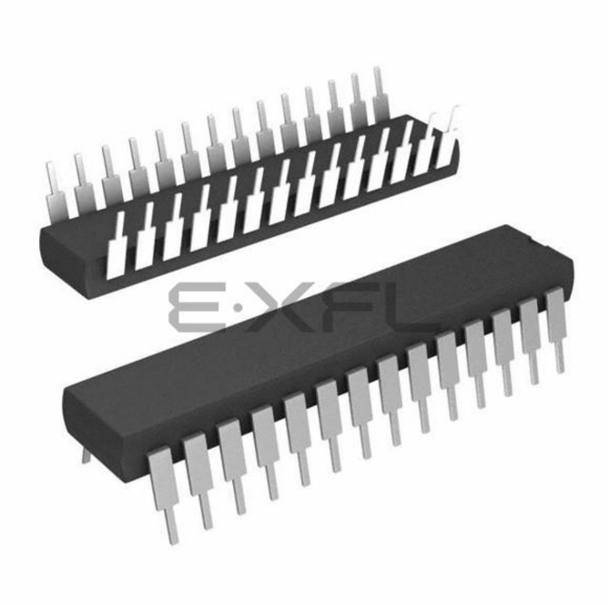


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f73-i-sp

1.0 DEVICE OVERVIEW

This document contains device specific information about the following devices:

- PIC16F73
- PIC16F74
- PIC16F76
- PIC16F77

PIC16F73/76 devices are available only in 28-pin packages, while PIC16F74/77 devices are available in 40-pin and 44-pin packages. All devices in the PIC16F7X family share common architecture, with the following differences:

- The PIC16F73 and PIC16F76 have one-half of the total on-chip memory of the PIC16F74 and PIC16F77
- The 28-pin devices have 3 I/O ports, while the 40/44-pin devices have 5
- The 28-pin devices have 11 interrupts, while the 40/44-pin devices have 12
- The 28-pin devices have 5 A/D input channels, while the 40/44-pin devices have 8
- The Parallel Slave Port is implemented only on the 40/44-pin devices

The available features are summarized in Table 1-1. Block diagrams of the PIC16F73/76 and PIC16F74/77 devices are provided in Figure 1-1 and Figure 1-2, respectively. The pinouts for these device families are listed in Table 1-2 and Table 1-3.

Additional information may be found in the PICmicro™ Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

TABLE 1-1: PIC16F7X DEVICE FEATURES

Key Features	PIC16F73	PIC16F74	PIC16F76	PIC16F77
Operating Frequency	DC - 20 MHz	DC - 20 MHz	DC - 20 MHz	DC - 20 MHz
RESETS (and Delays)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)
FLASH Program Memory (14-bit words)	4K	4K	8K	8K
Data Memory (bytes)	192	192	368	368
Interrupts	11	12	11	12
I/O Ports	Ports A,B,C	Ports A,B,C,D,E	Ports A,B,C	Ports A,B,C,D,E
Timers	3	3	3	3
Capture/Compare/PWM Modules	2	2	2	2
Serial Communications	SSP, USART	SSP, USART	SSP, USART	SSP, USART
Parallel Communications	—	PSP	—	PSP
8-bit Analog-to-Digital Module	5 Input Channels	8 Input Channels	5 Input Channels	8 Input Channels
Instruction Set	35 Instructions	35 Instructions	35 Instructions	35 Instructions
Packaging	28-pin DIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin PLCC 44-pin TQFP	28-pin DIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin PLCC 44-pin TQFP

3.3 Reading the FLASH Program Memory

A program memory location may be read by writing two bytes of the address to the PMADR and PMADRH registers and then setting control bit RD (PMCON1<0>). Once the read control bit is set, the microcontroller will use the next two instruction cycles to read the data. The data is available in the PMDATA and PMDATH registers after the second `NOP` instruction. Therefore, it can be read as two bytes in the following instructions. The PMDATA and PMDATH registers will hold this value until the next read operation.

3.4 Operation During Code Protect

FLASH program memory has its own code protect mechanism. External Read and Write operations by programmers are disabled if this mechanism is enabled.

The microcontroller can read and execute instructions out of the internal FLASH program memory, regardless of the state of the code protect configuration bits.

EXAMPLE 3-1: FLASH PROGRAM READ

```
            BSF      STATUS, RP1     ;
            BCF      STATUS, RP0     ; Bank 2
            MOVF     ADDRH, W        ;
            MOVWF    PMADRH          ; MSByte of Program Address to read
            MOVF     ADDRL, W        ;
            MOVWF    PMADR           ; LSByte of Program Address to read
            BSF      STATUS, RP0     ; Bank 3 Required

Required    BSF      PMCON1, RD      ; EEPROM Read Sequence
Sequence    NOP                      ; memory is read in the next two cycles after BSF PMCON1,RD
            NOP                      ;

            BCF      STATUS, RP0     ; Bank 2
            MOVF     PMDATA, W       ; W = LSByte of Program PMDATA
            MOVF     PMDATH, W       ; W = MSByte of Program PMDATA
```

TABLE 3-1: REGISTERS ASSOCIATED WITH PROGRAM FLASH

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
10Dh	PMADR	Address Register Low Byte								xxxx xxxx	uuuu uuuu
10Fh	PMADRH	—	—	—	Address Register High Byte					xxxx xxxx	uuuu uuuu
10Ch	PMDATA	Data Register Low Byte								xxxx xxxx	uuuu uuuu
10Eh	PMDATH	—	—	Data Register High Byte						xxxx xxxx	uuuu uuuu
18Ch	PMCON1	—(1)	—	—	—	—	—	—	RD	1--- ---0	1--- ---0

Legend: x = unknown, u = unchanged, r = reserved, - = unimplemented read as '0'. Shaded cells are not used during FLASH access.
Note 1: This bit always reads as a ‘1’.

4.6 Parallel Slave Port

The Parallel Slave Port (PSP) is not implemented on the PIC16F73 or PIC16F76.

PORTD operates as an 8-bit wide Parallel Slave Port, or Microprocessor Port, when control bit PSPMODE (TRISE<4>) is set. In Slave mode, it is asynchronously readable and writable by an external system using the read control input pin RE0/$\overline{\text{RD}}$, the write control input pin RE1/$\overline{\text{WR}}$, and the chip select control input pin RE2/$\overline{\text{CS}}$.

The PSP can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting bit PSPMODE enables port pin RE0/$\overline{\text{RD}}$ to be the $\overline{\text{RD}}$ input, RE1/$\overline{\text{WR}}$ to be the $\overline{\text{WR}}$ input and RE2/$\overline{\text{CS}}$ to be the $\overline{\text{CS}}$ (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (i.e., set). The A/D port configuration bits PCFG3:PCFG0 (ADCON1<3:0>) must be set to configure pins RE2:RE0 as digital I/O.

There are actually two 8-bit latches, one for data output (external reads) and one for data input (external writes). The firmware writes 8-bit data to the PORTD output data latch and reads data from the PORTD input data latch (note that they have the same address). In this mode, the TRISD register is ignored, since the external device is controlling the direction of data flow.

An external write to the PSP occurs when the $\overline{\text{CS}}$ and $\overline{\text{WR}}$ lines are both detected low. Firmware can read the actual data on the PORTD pins during this time. When either the CS or WR lines become high (level triggered), the data on the PORTD pins is latched, and the Input Buffer Full (IBF) status flag bit (TRISE<7>) and interrupt flag bit PSPIF (PIR1<7>) are set on the Q4 clock cycle, following the next Q2 cycle to signal the write is complete (Figure 4-9). Firmware clears the IBF flag by reading the latched PORTD data, and clears the PSPIF bit.

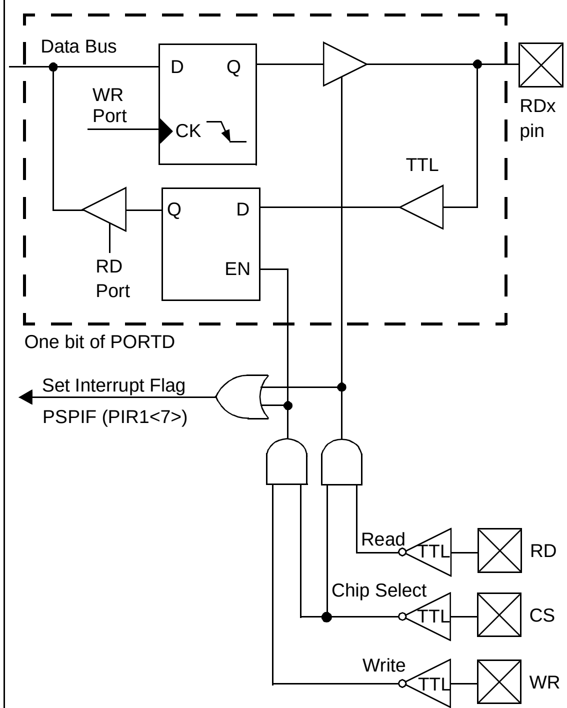
The Input Buffer Overflow (IBOV) status flag bit (TRISE<5>) is set if an external write to the PSP occurs while the IBF flag is set from a previous external write. The previous PORTD data is overwritten with the new data. IBOV is cleared by reading PORTD and clearing IBOV.

A read from the PSP occurs when both the $\overline{\text{CS}}$ and $\overline{\text{RD}}$ lines are detected low. The data in the PORTD output latch is output to the PORTD pins. The Output Buffer Full (OBF) status flag bit (TRISE<6>) is cleared immediately (Figure 4-10), indicating that the PORTD latch is being read, or has been read by the external bus. If firmware writes new data to the output latch during this time, it is immediately output to the PORTD pins, but OBF will remain cleared.

When either the $\overline{\text{CS}}$ or $\overline{\text{RD}}$ pins are detected high, the PORTD outputs are disabled, and the interrupt flag bit PSPIF is set on the Q4 clock cycle following the next Q2 cycle, indicating that the read is complete. OBF remains low until firmware writes new data to PORTD.

When not in PSP mode, the IBF and OBF bits are held clear. Flag bit IBOV remains unchanged. The PSPIF bit must be cleared by the user in firmware; the interrupt can be disabled by clearing the interrupt enable bit PSPIE (PIE1<7>).

FIGURE 4-8: PORTD AND PORTE BLOCK DIAGRAM (PARALLEL SLAVE PORT)



Note: I/O pin has protection diodes to VDD and VSS.

6.0 TIMER1 MODULE

The Timer1 module is a 16-bit timer/counter consisting of two 8-bit registers (TMR1H and TMR1L), which are readable and writable. The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow, which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

Timer1 can operate in one of two modes:

- As a timer
- As a counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In Timer mode, Timer1 increments every instruction cycle. In Counter mode, it increments on every rising edge of the external clock input.

Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Timer1 also has an internal "RESET input". This RESET can be generated by either of the two CCP modules as the special event trigger (see Sections 8.1 and 8.2). Register 6-1 shows the Timer1 Control register.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RC1/T1OSI/CCP2 and RC0/T1OSO/T1CKI pins become inputs. That is, the TRISC<1:0> value is ignored and these pins read as '0'.

Additional information on timer modules is available in the PICmicro™ Mid-Range MCU Family Reference Manual (DS33023).

REGISTER 6-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
`11` = 1:8 Prescale value
`10` = 1:4 Prescale value
`01` = 1:2 Prescale value
`00` = 1:1 Prescale value

bit 3 **T1OSCEN**: Timer1 Oscillator Enable Control bit
`1` = Oscillator is enabled
`0` = Oscillator is shut-off (the oscillator inverter is turned off to eliminate power drain)

bit 2 **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit
<u>TMR1CS = 1:</u>
`1` = Do not synchronize external clock input
`0` = Synchronize external clock input
<u>TMR1CS = 0:</u>
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1 **TMR1CS**: Timer1 Clock Source Select bit
`1` = External clock from pin RC0/T1OSO/T1CKI (on the rising edge)
`0` = Internal clock (FOSC/4)

bit 0 **TMR1ON**: Timer1 On bit
`1` = Enables Timer1
`0` = Stops Timer1

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 9-1: REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh. 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in SPI mode.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F73/76; always maintain these bits clear.

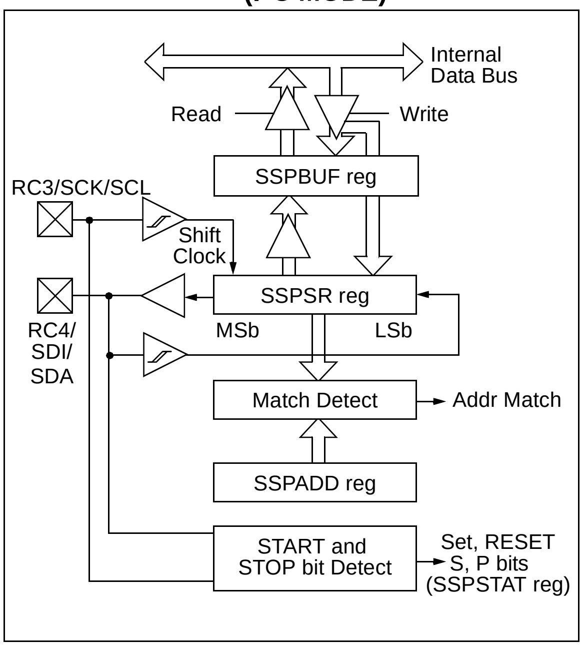
9.3 SSP I^{2}C Operation

The SSP module in I^{2}C mode, fully implements all slave functions, except general call support, and provides interrupts on START and STOP bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing.

Two pins are used for data transfer. These are the RC3/SCK/SCL pin, which is the clock (SCL), and the RC4/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISC<4:3> bits.

The SSP module functions are enabled by setting SSP enable bit SSPEN (SSPCON<5>).

FIGURE 9-5: SSP BLOCK DIAGRAM (I^{2}C MODE)



The SSP module has five registers for I^{2}C operation. These are the:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) - Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I^{2}C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I^{2}C modes to be selected:

- I^{2}C Slave mode (7-bit address)
- I^{2}C Slave mode (10-bit address)
- I^{2}C Slave mode (7-bit address), with START and STOP bit interrupts enabled to support Firmware Master mode
- I^{2}C Slave mode (10-bit address), with START and STOP bit interrupts enabled to support Firmware Master mode
- I^{2}C START and STOP bit interrupts enabled to support Firmware Master mode, Slave is IDLE

Selection of any I^{2}C mode with the SSPEN bit set, forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits. Pull-up resistors must be provided externally to the SCL and SDA pins for proper operation of the I^{2}C module.

Additional information on SSP I^{2}C operation can be found in the PICmicro™ Mid-Range MCU Family Reference Manual (DS33023A).

9.3.1 SLAVE MODE

In Slave mode, the SCL and SDA pins must be configured as inputs (TRISC<4:3> set). The SSP module will override the input state with the output data when required (slave-transmitter).

When an address is matched, or the data transfer after an address match is received, the hardware automatically will generate the Acknowledge ($\overline{\text{ACK}}$) pulse, and then load the SSPBUF register with the received value currently in the SSPSR register.

There are certain conditions that will cause the SSP module not to give this $\overline{\text{ACK}}$ pulse. They include (either or both):

a) The buffer full bit BF (SSPSTAT<0>) was set before the transfer was received.

b) The overflow bit SSPOV (SSPCON<6>) was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF (PIR1<3>) is set. Table 9-2 shows what happens when a data transfer byte is received, given the status of bits BF and SSPOV. The shaded cells show the condition where user software did not properly clear the overflow condition. Flag bit BF is cleared by reading the SSPBUF register, while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the I^{2}C specification, as well as the requirements of the SSP module, are shown in timing parameter #100 and parameter #101.

TABLE 10-3: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE	FOSC = 20 MHz			FOSC = 16 MHz			FOSC = 10 MHz		
	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)
1200	1,221	1.73%	255	1,202	0.16%	207	1,202	0.16%	129
2400	2,404	0.16%	129	2,404	0.16%	103	2,404	0.16%	64
9600	9,470	-1.36%	32	9,615	0.16%	25	9,766	1.73%	15
19,200	19,531	1.73%	15	19,231	0.16%	12	19,531	1.73%	7
38,400	39,063	1.73%	7	35,714	-6.99%	6	39,063	1.73%	3
57,600	62,500	8.51%	4	62,500	8.51%	3	52,083	-9.58%	2
76,800	78,125	1.73%	3	83,333	8.51%	2	78,125	1.73%	1
96,000	104,167	8.51%	2	83,333	-13.19%	2	78,125	-18.62%	1
115,200	104,167	-9.58%	2	125,000	8.51%	1	78,125	-32.18%	1
250,000	312,500	25.00%	0	250,000	0.00%	0	156,250	-37.50%	0

BAUD RATE	FOSC = 4 MHz			FOSC = 3.6864 MHz			FOSC = 3.579545 MHz		
	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)
300	300	0.16%	207	300	0.00%	191	301	0.23%	185
1200	1,202	0.16%	51	1,200	0.00%	47	1,190	-0.83%	46
2400	2,404	0.16%	25	2,400	0.00%	23	2,432	1.32%	22
9600	8,929	-6.99%	6	9,600	0.00%	5	9,322	-2.90%	5
19,200	20,833	8.51%	2	19,200	0.00%	2	18,643	-2.90%	2
38,400	31,250	-18.62%	1	28,800	-25.00%	1	27,965	-27.17%	1
57,600	62,500	8.51%	0	57,600	0.00%	0	55,930	-2.90%	0
76,800	62,500	-18.62%	0	—	—	—	—	—	—

TABLE 10-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE	FOSC = 20 MHz			FOSC = 16 MHz			FOSC = 10 MHz		
	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)
2400	—	—	—	—	—	—	2,441	1.73%	255
9600	9,615	0.16%	129	9,615	0.16%	103	9,615	0.16%	64
19,200	19,231	0.16%	64	19,231	0.16%	51	18,939	-1.36%	32
38,400	37,879	-1.36%	32	38,462	0.16%	25	39,063	1.73%	15
57,600	56,818	-1.36%	21	58,824	2.12%	16	56,818	-1.36%	10
76,800	78,125	1.73%	15	76,923	0.16%	12	78,125	1.73%	7
96,000	96,154	0.16%	12	100,000	4.17%	9	89,286	-6.99%	6
115,200	113,636	-1.36%	10	111,111	-3.55%	8	125,000	8.51%	4
250,000	250,000	0.00%	4	250,000	0.00%	3	208,333	-16.67%	2
300,000	312,500	4.17%	3	333,333	11.11%	2	312,500	4.17%	1

BAUD RATE (K)	FOSC = 4 MHz			FOSC = 3.6864 MHz			FOSC = 3.579545 MHz		
	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)	BAUD	% ERROR	SPBRG VALUE (DECIMAL)
1200	1,202	0.16%	207	1,200	0.00%	191	1,203	0.23%	185
2400	2,404	0.16%	103	2,400	0.00%	95	2,406	0.23%	92
9600	9,615	0.16%	25	9,600	0.00%	23	9,727	1.32%	22
19,200	19,231	0.16%	12	19,200	0.00%	11	18,643	-2.90%	11
38,400	35,714	-6.99%	6	38,400	0.00%	5	37,287	-2.90%	5
57,600	62,500	8.51%	3	57,600	0.00%	3	55,930	-2.90%	3
76,800	83,333	8.51%	2	76,800	0.00%	2	74,574	-2.90%	2
96,000	83,333	-13.19%	2	115,200	20.00%	1	111,861	16.52%	1
115,200	125,000	8.51%	1	115,200	0.00%	1	111,861	-2.90%	1
250,000	250,000	0.00%	0	230,400	-7.84%	0	223,722	-10.51%	0

10.2 USART Asynchronous Mode

In this mode, the USART uses standard non-return-to-zero (NRZ) format (one START bit, eight or nine data bits, and one STOP bit). The most common data format is 8-bits. An on-chip, dedicated, 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The USART's transmitter and receiver are functionally independent, but use the same data format and baud rate. The baud rate generator produces a clock, either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

10.2.1 USART ASYNCHRONOUS TRANSMITTER

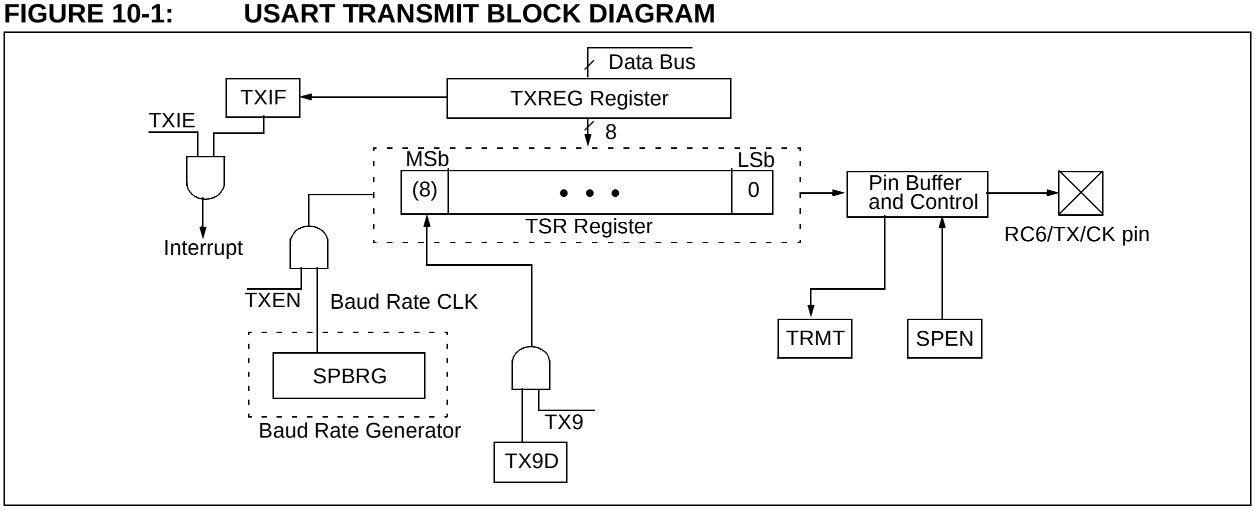
The USART transmitter block diagram is shown in Figure 10-1. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data by firmware. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register, the TXREG register is empty. One instruction cycle later, flag bit TXIF (PIR1<4>) and flag bit TRMT (TXSTA<1>) are set. The TXIF interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set, regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit, which is set one instruction cycle after the TSR register becomes empty, and is cleared one instruction cycle after the TSR register is loaded. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

Note 1:	The TSR register is not mapped in data memory, so it is not available to the user.
2:	Flag bit TXIF is set when enable bit TXEN is set. TXIF is cleared by loading TXREG.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 10-2). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally, when transmission is first started, the TSR register is empty. At that point, transfer to the TXREG register will result in an immediate transfer to TSR, resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 10-3). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. As a result, the RC6/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit may be loaded in the TSR register.

FIGURE 10-1: USART TRANSMIT BLOCK DIAGRAM



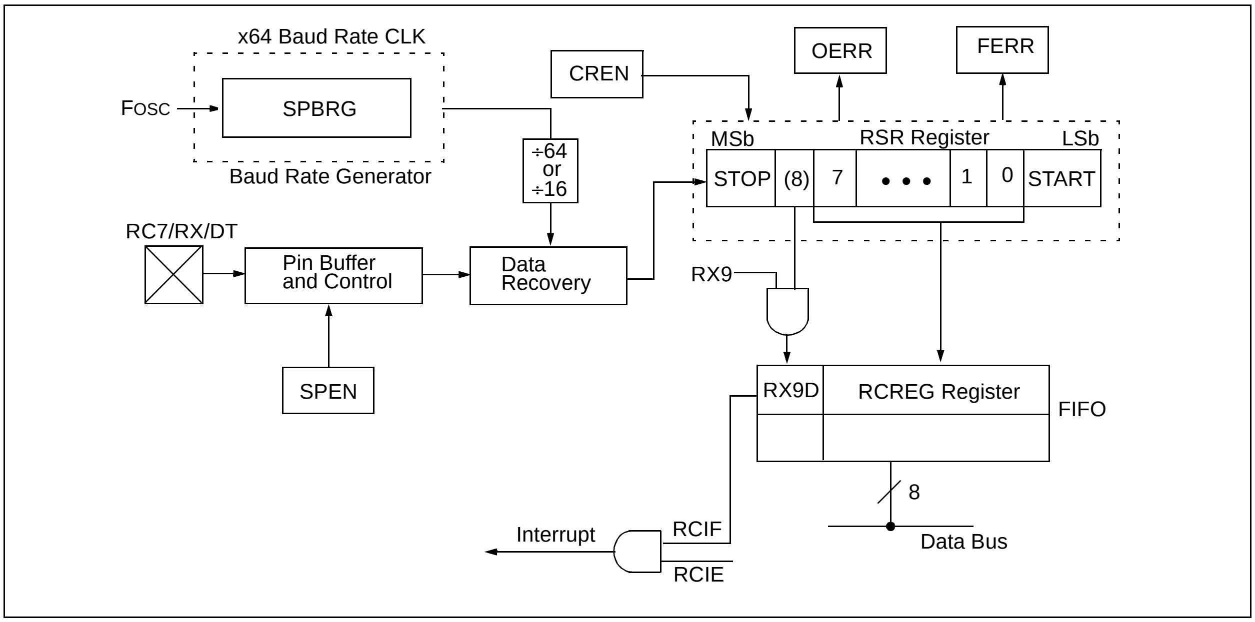
10.2.2 USART ASYNCHRONOUS RECEIVER

The receiver block diagram is shown in Figure 10-4. The data is received on the RC7/RX/DT pin and drives the data recovery block. The data recovery block is actually a high speed shifter operating at x16 times the baud rate, whereas the main receive serial shifter operates at the bit rate, or at FOSC.

Once Asynchronous mode is selected, reception is enabled by setting bit CREN (RCSTA<4>).

The heart of the receiver is the receive (serial) shift register (RSR). After sampling the STOP bit, the received data in the RSR is transferred to the RCREG register (if it is empty). If the transfer is complete, flag bit RCIF (PIR1<5>) is set. The actual interrupt can be enabled/disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read only bit which is cleared by the hardware. It is cleared when the RCREG register has been read and is empty. The RCREG is a double buffered register (i.e., it is a two deep FIFO). It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting to the RSR register. On the detection of the STOP bit of the third byte, if the RCREG register is still full, the overrun error bit OERR (RCSTA<1>) will be set. The word in the RSR will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun bit OERR has to be cleared in software. This is done by resetting the receive logic (CREN is cleared and then set). If bit OERR is set, transfers from the RSR register to the RCREG register are inhibited and no further data will be received, therefore, it is essential to clear error bit OERR if it is set. Framing error bit FERR (RCSTA<2>) is set if a STOP bit is detected as clear. Bit FERR and the 9th receive bit are buffered the same way as the receive data. Reading the RCREG will load bits RX9D and FERR with new values, therefore, it is essential for the user to read the RCSTA register before reading RCREG register, in order not to lose the old FERR and RX9D information.

FIGURE 10-4: USART RECEIVE BLOCK DIAGRAM



NOTES:

REGISTER 12-1: CONFIGURATION WORD (ADDRESS 2007h)(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/P-1	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	—	—	—	—	BOREN	—	CP0	$\overline{\text{PWRTEN}}$	WDTEN	FOSC1	FOSC0
bit13													bit0

bit 13-7 **Unimplemented:** Read as ‘1’

bit 6 **BOREN**: Brown-out Reset Enable bit
1 = BOR enabled
0 = BOR disabled

bit 5 **Unimplemented:** Read as ‘1’

bit 4 **CP0:** FLASH Program Memory Code Protection bit
1 = Code protection off
0 = All memory locations code protected

bit 3 **$\overline{\text{PWRTEN}}$**: Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 2 **WDTEN**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0 **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: The erased (unprogrammed) value of the configuration word is 3FFFh.

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’
- n = Value when device is unprogrammed		u = Unchanged from programmed state

12.14 Power-down Mode (SLEEP)

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit (STATUS<3>) is cleared, the $\overline{TO}$ (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD} or V_{SS}, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D and disable external clocks. Pull all I/O pins that are hi-impedance inputs, high or low externally, to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should also be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

12.14.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on $\overline{MCLR}$ pin.
2. Watchdog Timer wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change or a Peripheral Interrupt.

External $\overline{MCLR}$ Reset will cause a device RESET. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if a WDT time-out occurred and caused wake-up.

The following peripheral interrupts can wake the device from SLEEP:

1. PSP read or write (PIC16F74/77 only).
2. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
3. CCP Capture mode interrupt.
4. Special event trigger (Timer1 in Asynchronous mode, using an external clock).
5. SSP (START/STOP) bit detect interrupt.
6. SSP transmit or receive in Slave mode (SPI/I^2C).
7. USART RX or TX (Synchronous Slave mode).
8. A/D conversion (when A/D clock source is RC).

Other peripherals cannot generate interrupts, since during SLEEP, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs, regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

12.14.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from SLEEP. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

SWAPF — Swap Nibbles in f

Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (destination<7:4>), (f<7:4>) → (destination<3:0>)
Status Affected:	None
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed in register 'f'.

XORLW — Exclusive OR Literal with W

Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF — Exclusive OR W with f

Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

FIGURE 15-1: PIC16F7X VOLTAGE-FREQUENCY GRAPH

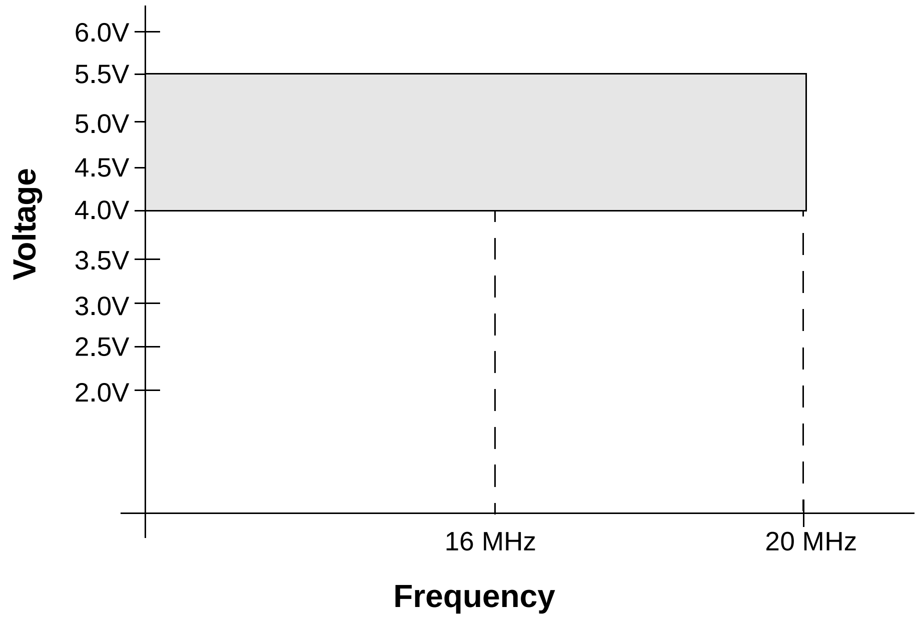
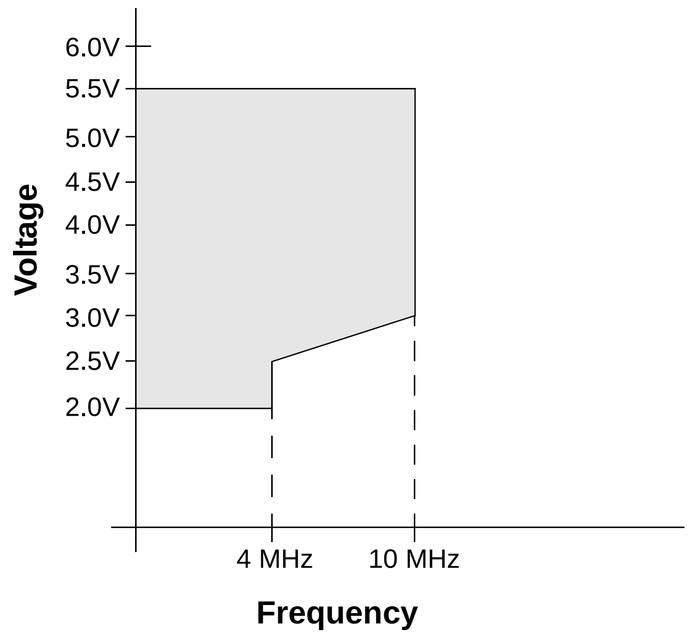


FIGURE 15-2: PIC16LF7X VOLTAGE-FREQUENCY GRAPH



FMAX = (12 MHz/V) (VDDAPPMIN - 2.5V) + 4 MHz

Note 1: VDDAPPMIN is the minimum voltage of the PICmicro® device in the application.

2: FMAX has a maximum frequency of 10 MHz.

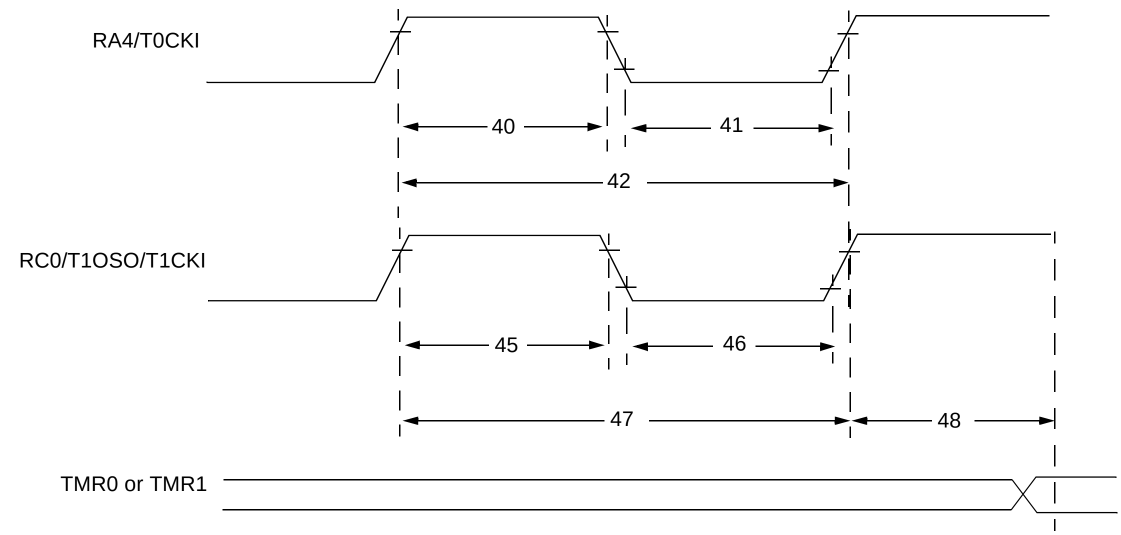
15.1 DC Characteristics: PIC16F73/74/76/77 (Industrial, Extended) PIC16LF73/74/76/77 (Industrial)

PIC16LF73/74/76/77 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC16F73/74/76/77 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LF7X	2.5 2.2 2.0	— — —	5.5 5.5 5.5	V V V	A/D in use, -40°C to +85°C A/D in use, 0°C to +85°C A/D not used, -40°C to +85°C
D001 D001A		PIC16F7X	4.0 VBOR*	- -	5.5 5.5	V V	All configurations BOR enabled **(Note 7)**
D002*	VDR	**RAM Data Retention Voltage (Note 1)**	-	1.5	-	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	-	VSS	-	V	See section on Power-on Reset for details
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset Voltage**	3.65	4.0	4.35	V	BODEN bit in configuration word enabled

Legend: Shading of rows is to assist in readability of of the table.
* These parameters are characterized but not tested.
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.
2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from-rail to-rail; all I/O pins tri-stated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.
5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.
6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.
7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

FIGURE 15-8: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 15-3 for load conditions.

TABLE 15-4: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
47*	Tt1P	T1CKI Input Period	Synchronous	Standard(**F**)	Greater of: 30 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 2, 4, 8)
				Extended(**LF**)	Greater of: 50 or $\frac{T_{CY} + 40}{N}$				N = prescale value (1, 2, 4, 8)
			Asynchronous	Standard(**F**)	60	—	—	ns	
				Extended(**LF**)	100	—	—	ns	
	Ft1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from External Clock Edge to Timer Increment			2 TOSC	—	7 TOSC	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 15-9: I²C BUS DATA REQUIREMENTS

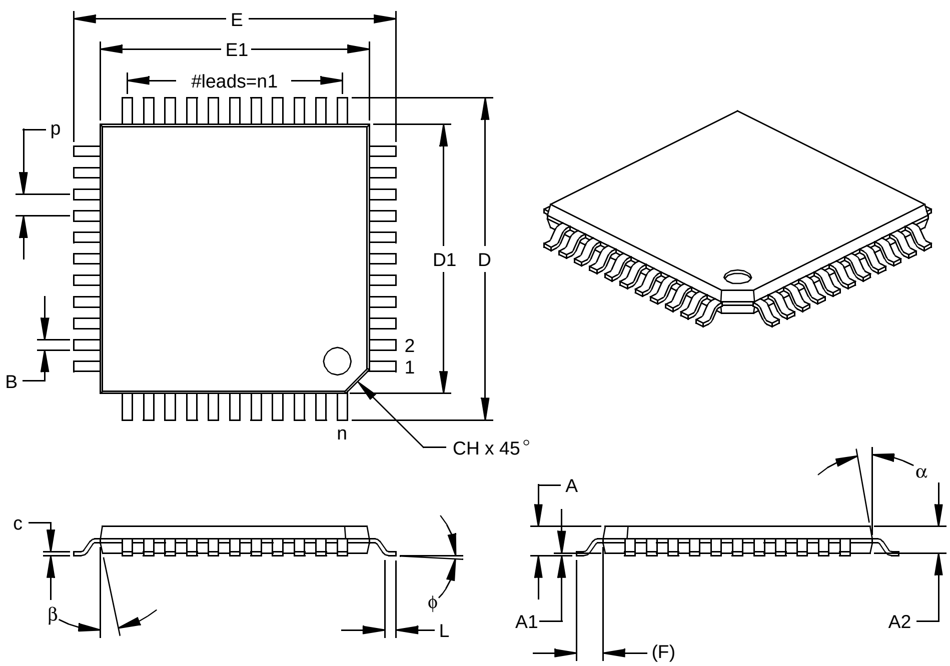
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
90*	TSU:STA	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for Repeated START condition
			400 kHz mode	0.6	—	μs	
91*	THD:STA	START condition hold time	100 kHz mode	4.0	—	μs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	CB	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A Fast mode (400 kHz) I²C bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

44-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)

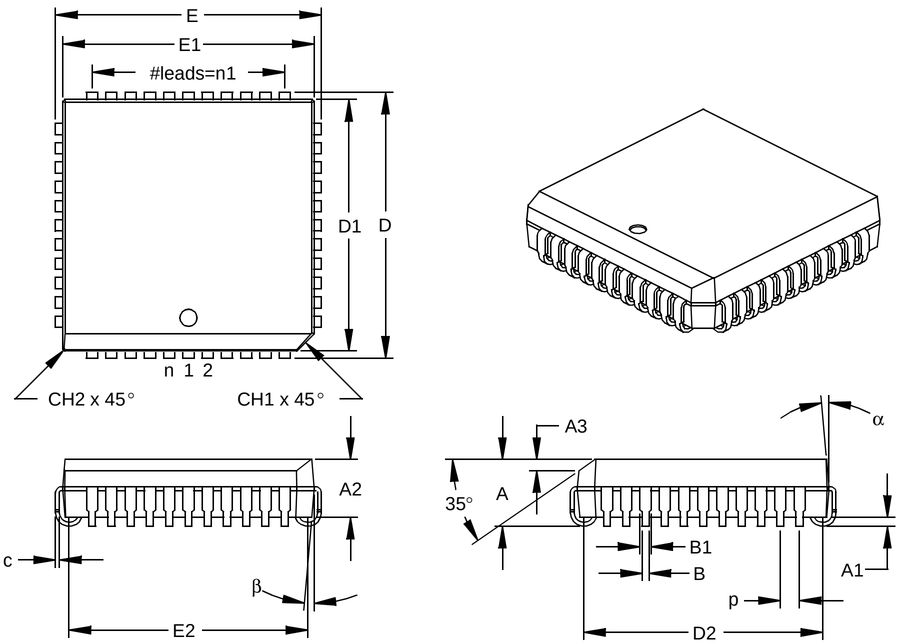


Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.031			0.80	
Pins per Side	n1		11			11	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	(F)		.039		1.00		
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.463	.472	.482	11.75	12.00	12.25
Overall Length	D	.463	.472	.482	11.75	12.00	12.25
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.012	.015	.017	0.30	0.38	0.44
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: MS-026
Drawing No. C04-076

44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-048